Rear Door Heat Exchanger (RDHx)

Gradian's active rear-door heat exchangers remove heat directly at the rack, supporting higher rack densities while reducing room-level air handling requirements. Quick-connect, clamp-mounted liquid interfaces enable fast installation and simplified service. Our DeepCoolAI technology features integrated monitoring and open communication protocols ready for seamless integration with existing data center infrastructure.



KEY FEATURES

- N+1 fan redundancy: Maintains operation during a fan failure for high availability
- Adaptive fan control: High efficiency EC fans with Fixed-speed or variable-speed operation to match rack load
- Quick-connect liquid interface with top or bottom connection options and clamp-mounted connections for fast install/service
- High-performance coil is equipped with leak detection sensor and liquid collection tray with drain port
- All models come with optional interface frame to support cabinet door installation with top outlet piping for liquid cooled AI racks

Designed for:

- High-density AI/HPC racks: Rack-level heat capture for demanding compute loads
- Liquid-cooled cabinets: Pair with cabinet-mounted or rack-mounted CDUs
- Manifold connectivity: 100 kW and 200 kW models include an adapter to connect hoses to in-rack manifolds

SPECIFICATIONS

CAPACITY
30 – 200 kW

CFM
11,000 CFM

POWER SUPPLY
230 - 480 V / 1 ph / 60 Hz

CONTROLS AND COMMUNICATION
RS-485 and RJ45 interfaces with Modbus RTU and Modbus TCP/IP

COOLANT TYPE
Water or Water/glycol solutions

MAXIMUM POWER CONSUMPTION
5-7 kW

FAN TYPE
High efficiency EC fans

REDUNDANCY
N+1 hot swappable fans

COMPATIBLE RACK SIZE
42-52 U | 600mm to 800mm width

Specifications may vary based on model and capacity.